



SOT521-1

plastic DIL-bent-SIL power package; 27 leads (lead length 7.7 mm)

8 February 2016

Package information

1. Package summary

Terminal position code	Z (zig-zag)
Package type descriptive code	DBS27P
Package type industry code	DBS27P
Package style descriptive code	DBS (DIL-bent-SIL)
Package style suffix code	P (power)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	24-4-2002

Table 1. Package summary

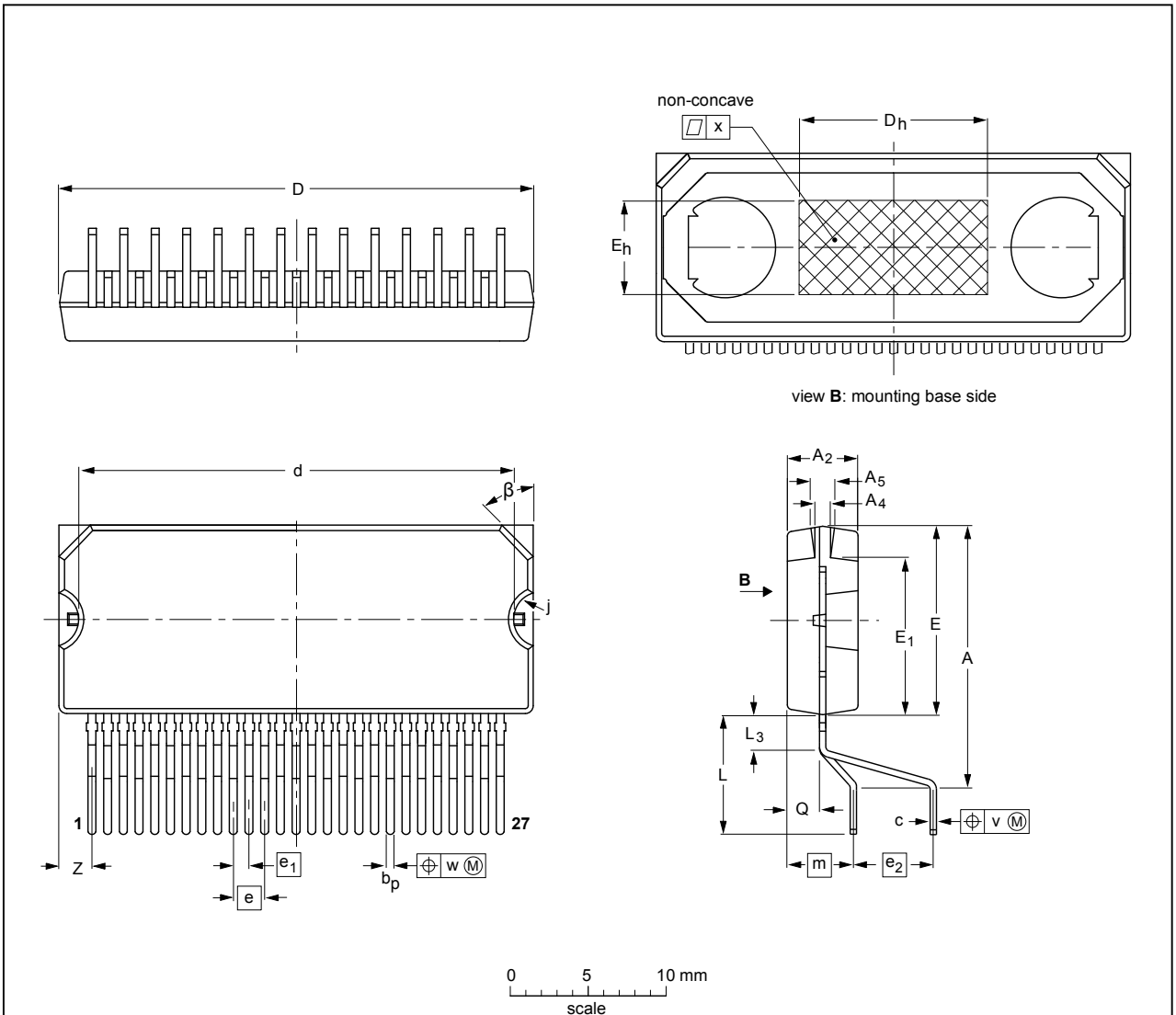
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	29.9	-	30.2	30.4	mm
E	package width	11.8	-	12	12.2	mm
A	seated height	15.5	-	17	17	mm
A ₂	package height	4.3	-	4.45	4.6	mm
n ₂	actual quantity of termination	-	-	27	-	



2. Package outline

DBS27P: plastic DIL-bent-SIL power package; 27 leads (lead length 7.7 mm)

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DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₂	A ₄	A ₅	b _p	c	D ⁽¹⁾	d	D _h	E ⁽¹⁾	e	e ₁	e ₂	E _h	E ₁	j	L	L ₃	m	Q	v	w	x	β	z ⁽¹⁾
mm	17.0	4.6	1.15	1.65	0.60	0.5	30.4	28.0	12	12.2	2	1	4	6	10.15	1.85	8.4	2.4	4.3	2.1	0.6	0.25	0.03	45°	2.4
	15.5	4.3	0.85	1.35	0.45	0.3	29.9	27.5		11.8					9.85	1.65	7.0	1.6		1.8					1.8

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT521-1						99-01-05 02-04-24

Fig. 1. Package outline DBS27P (SOT521-1)

3. Legal information

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